To the Honorable Comr. 10079907 1. Name of conveying party(ies): CHUNG-HSING TZU CHUNG-HSING TZU CHUNG-HSING TZU Additional name(s) of conveying party(ies) attached? I Yes IN Nature of conveyance: Image: Assignment Image: Merger	2. Name and address of receiving party(ies) Name:
CHUNG-HSING TZU Additional name(s) of conveying party(ies) attached? • Yes IN 3. Nature of conveyance:	Name: SAMPO SEMICONDUCTOR CORPORATION Address: 1F, No. 1, Kao-Pin Sec., Chung-Feng Rd., Lung Ta
	Tao Yuan Hsien, Taiwan, R.O.C
Change of Chang	Name City: Tao Yuan Country: Taiwan, F Additional name(s) & address(es) attached? Q Yes X No
 Application number(s) or patent number(s): If this document is being filed together with a new a A. Patent Application No.(s) 	oplication, the execution date of the application is: 7/29/98 B. Patent No.(s)
Additional m	umbers attached? 🖸 Yes OI No
 Name and address of party to whom correspondence concerning document should be mailed: 	6. Total number of applications and patents involved:
Name: MORTON J. ROSENBERG, ESQ.	7. Total fee (37 CFR 3.41)\$ 40.00
BILKER	Authorized to be charged to deposit account
Street Address: 3444 ELLICOTT CENTER D	RIVE 8. Deposit account number:
City: ELLICOTT CITY State: MD ZIP: 210	(Attach duplicate copy of this page if paying by deposit account)
DC	NOT USE THIS SPACE
the original document. MORTON J. ROSENBERG	g information is true and correct and any attached copy is a true copy the signature of the second
Mail documents to be record	including cover sheet, attachments, and document:

REEL: 9393 FRAME: 0448



() CHUNG-HSING TZU (FAMILY NAME: TZU)

(2)	
(3)	
(4)	
(5)	

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(6) Insert name of Assignee

(1-5) Insert Name(s) of Inventor(s).

(6) SAMPO SEMICONDUCTOR CORPORATION (PRESIDENT: STENC-TIEN CHEN)

(7) Insert address of Assignee

(?) 1F,NO.1,KAO-PING SEC., CHUNG-FENG RD., LUNG TAN

.TAO YUAN HSIEN, TAIWAN, R.O.C.

ON CHIP

(9) on JULY 29,1998

(hereinafter designated as the Assignee) the entire right, title and interest for the United States, its territories, dependencies and possessions, in the invention, and all applications for patent and any Letters Patent which may be granted therefor, known as

(8) SEMICONDUCTOR PACKAGING STRUCTURE WITH THE BAR

(8) Insert Identification of Invention, such as Title, Case Number or Foreign Application Number

for which the undersigned has (have) executed an application for patent in the United States of America

Foreign Application or Case No.

(9) Insert Date of Signing of Application

(10) Alternative identification for filed applications 1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient or essential to its full protection and title in and to the invention hereby transferred.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division or re-issue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such intereference.

3) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

4) The undersigned agree(s) to communicate to the Assignee or representatives thereof any facts known to me (us) respecting the invention and improvements thereof, and will, upon request, but without expense to me (us), testify in any legal proceedings regarding the invention.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith. 6) The undersigned hereby grant(s) the firm of Rosenberg identification which may be necessary or desirable in order to comply with the rules of the United State's Patent Office for recordation of this document.

7) This Assignment shall be binding upon my (our) heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns of the Assignee.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

(1)	Date JULY 29,1998	_ Name of Inventor	CHUNG-HSING	72 CHUNG-HSING	TZU
(3)	Date	_Name of Inventor			
(4)	Date	_Name of Inventor	i	• · · · ·	
(5)	Date	Name of Inventor			
Date	<u></u>	_ Witness			
Date					